United States Patent [19]

Murphy

[11] **Des. 258,281**

[45] ** **Feb. 17, 1981**

[54] **PANEL BOARD FOR INTEGRATED CIRCUIT PACKAGES**

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[73] Assignee: **Electronic Molding Corporation**, Woonsocket, R.I.

[**] Term: **14 Years**

[21] Appl. No.: **836,246**

[22] Filed: **Sep. 23, 1977**

[51] **Int. Cl.** .... **D13—03**

[52] **U.S. Cl.** **D13/12**

[58] **Field of Search** D13/12, 13, 24; 174/68.5

[56] **References Cited**

U.S. PATENT DOCUMENTS

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OTHER PUBLICATIONS

Api/Amp Terminal & Connector Handbook, 1972, p. 551, Standard Series Panels.

Electronic Molding Corp. Product Bulletin, FS-18, High Density Nurl-Loc, i.c. Panel.

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[57] **CLAIM**

The ornamental design for a panel board for integrated circuit packages, substantially as shown and described.

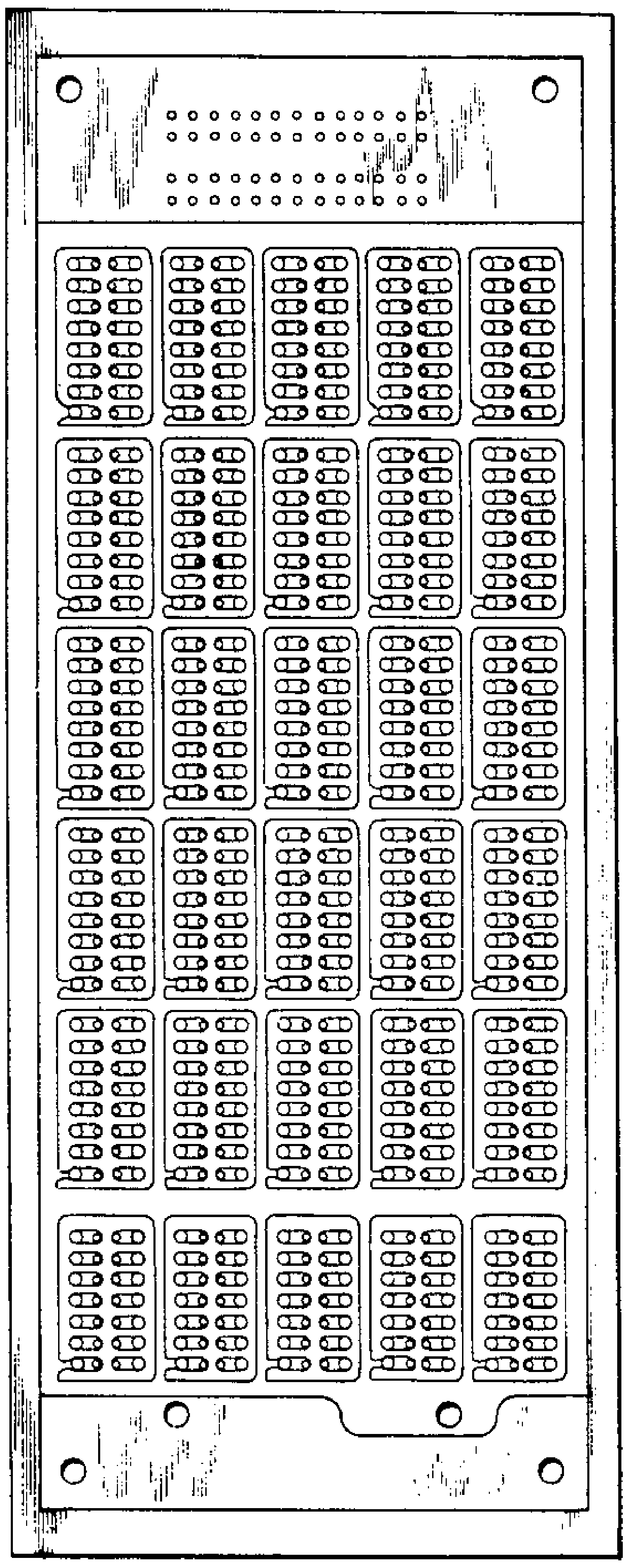
DESCRIPTION

FIG. **1** is a top plan view of one side of a panel board for integrated circuit packages showing my new design, the other side being substantially identical thereto;

FIG. **2** is a side elevational view thereof;

FIG. **3** is a fragmentary, front elevational view thereof, the board being broken away for convenience of illustration;

FIG. **4** is a fragmentary, rear elevational view thereof, the board being broken away for convenience of illustration.



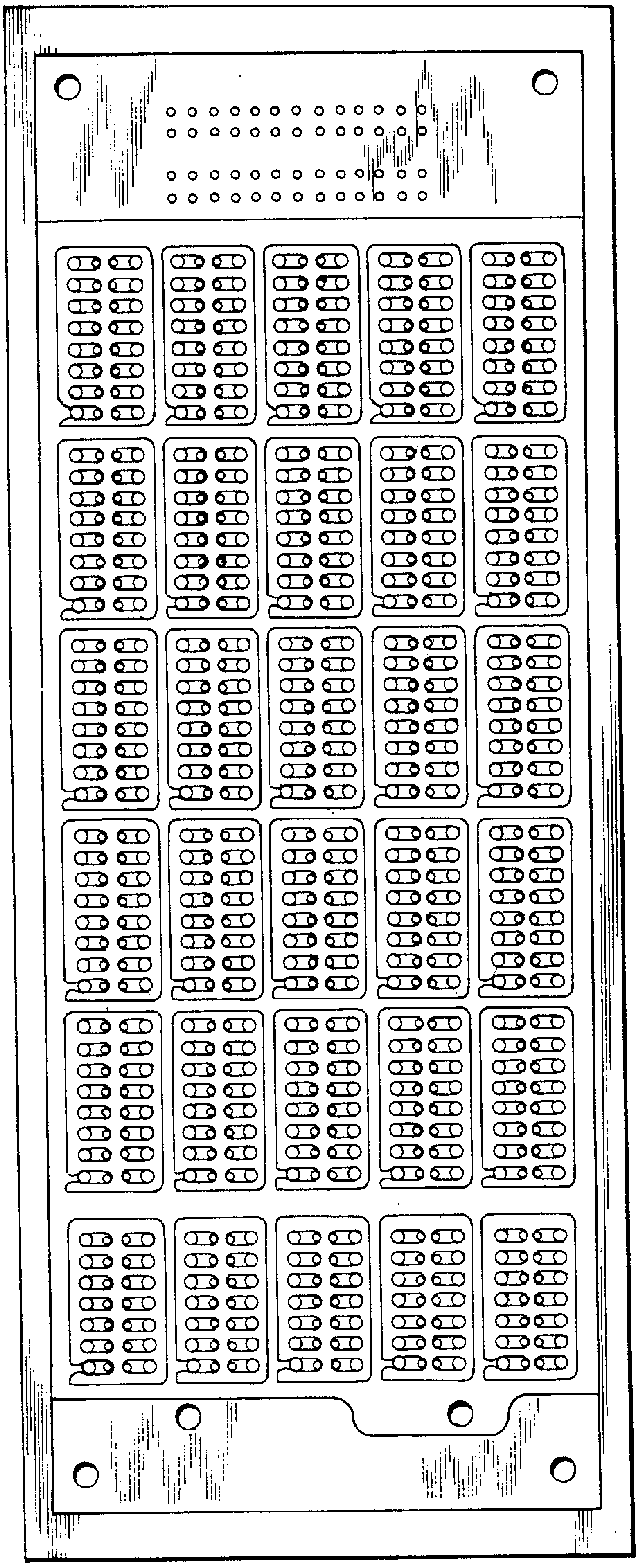


FIG. 1

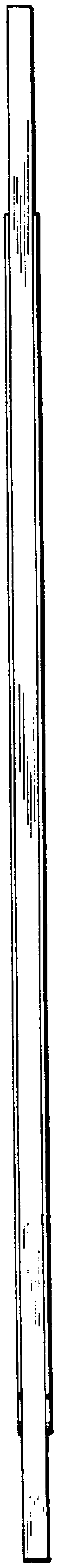


FIG. 2

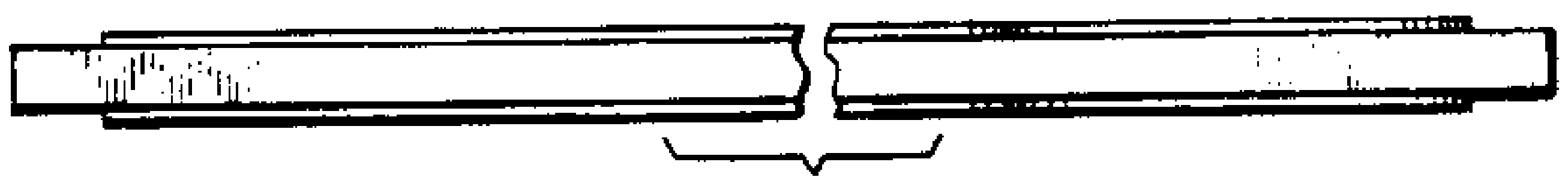


FIG. 3

FIG. 4